

ABSTRACT OF THE DISCLOSURE

The invention provides a method of plating an integrated circuit. An activation plate is positioned adjacent to at least one integrated circuit. The
5 integrated circuit includes a plurality of bond pads comprising a bond-pad metal, and the activation plate also comprises the bond-pad metal. A layer of electroless nickel is plated on the bond pads and the activation plate, and a layer of gold is plated over the layer of electroless nickel on the bond pads and the activation plate. An integrated circuit with bond pads plated using the activation
10 plate, and a system for plating an integrated circuit is also disclosed.